CMOD3003

SURFACE MOUNT LOW LEAKAGE SILICON SWITCHING DIODE



www.centralsemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMOD3003 type is a silicon switching diode manufactured by the epitaxial planar process, epoxy molded in a ULTRAmini™ surface mount package, designed for switching applications requiring a extremely low leakage diode.

MARKING CODE: 3C



MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Continuous Reverse Voltage	V_{R}	180	V
Average Rectified Current	IO	200	mA
Continuous Forward Current	I _F	600	mA
Peak Repetitive Forward Current	I _{FRM}	700	mA
Peak Forward Surge Current, tp=1.0µs	I _{FSM}	2.0	Α
Peak Forward Surge Current, tp=1.0s	I _{FSM}	1.0	Α
Power Dissipation	P_{D}	250	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	500	°C/W

$\textbf{ELECTRICAL CHARACTERISTICS:} \ (T_{\mbox{\scriptsize A}} = 25^{\circ}\mbox{C unless otherwise noted})$

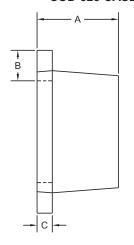
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I_{R}	V _R =125V		1.0	nA
I_{R}	V _R =125V, T _A =150°C		3.0	μΑ
I_{R}	V _R =180V		10	nA
I_{R}	V _R =180V, T _A =150°C		5.0	μΑ
BV_R	I _R =5.0μA	200		V
V_{F}	I _F =1.0mA	0.62	0.72	V
V_{F}	I _F =10mA	0.72	0.83	V
V_{F}	I _F =50mA	0.80	0.89	V
V_{F}	I _F =100mA	0.83	0.93	V
V_{F}	I _F =200mA	0.87	1.10	V
V_{F}	I _F =300mA	0.90	1.15	V
C _T	$V_R=0$, f=1.0MHz		4.0	pF

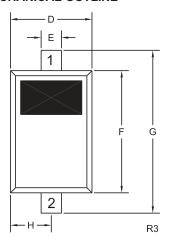
CMOD3003

SURFACE MOUNT LOW LEAKAGE SILICON SWITCHING DIODE



SOD-523 CASE - MECHANICAL OUTLINE





LEAD CODE:

- 1) Cathode 2) Anode

MARKING CODE: 3C

DIMENSIONS							
	INCHES		MILLIMETERS				
SYMBOL	MIN	MAX	MIN	MAX			
Α	0.020	0.031	0.50	0.80			
В	0.008	0.016	0.20	0.40			
С	0.002	0.008	0.05	0.20			
D	0.028	0.035	0.70	0.90			
E	0.008	0.014	0.20	0.35			
F	0.039	0.055	1.00	1.40			
G	0.055	0.071	1.40	1.80			
Н	0.016		0.40				
SOD-523 (REV: R3)							

R3 (11-April 2011)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp. 145 Adams Avenue Hauppauge, NY 11788 USA

Main Tel: (631) 435-1110 Main Fax: (631) 435-1824

Support Team Fax: (631) 435-3388

www.centralsemi.com

Worldwide Field Representatives: www.centralsemi.com/wwreps

Worldwide Distributors:

www.centralsemi.com/wwdistributors

For the latest version of Central Semiconductor's **LIMITATIONS AND DAMAGES DISCLAIMER**, which is part of Central's Standard Terms and Conditions of sale, visit: www.centralsemi.com/terms

www.centralsemi.com (001)